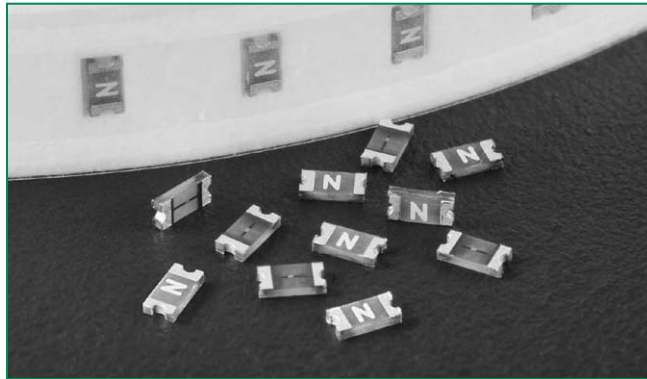


RoHS **467 Series Fuse**



Agency Approvals

Agency	Agency File Number	Ampere Range
	E10480	250mA - 5A
	LR29862	250mA - 5A

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	5 sec., Maximum
300%	0.2 sec., Maximum

Description

The 467 series fast-acting surface mount fuse series is an ultra small (0603 size) thin-film device designed for secondary protection of circuits used in space constrained applications such as hand-held portable electronic devices. This series is 100% lead-free and meet the requirements of the RoHS directive. New Halide Free 467 series fuses are available, orderable using the "HF" suffix. See Part Numbering section for additional information..

Features

- Compatible with lead-free solders and higher temperature profiles.
- High performance materials provide improved performance in elevated ambient temperature applications.
- Marked on top surface with code to allow amp rating identification without testing.
- Low profile for height sensitive applications.
- Flat top surface for pick-and-place operations.
- Element covering material is resistant to industry standard cleaning operations.
- Mounting pad and electrical performance is identical to Littelfuse 431 and 434 Series products.
- Alloy based element construction provides superior inrush withstand characteristics (I2t) over ceramic or glass based 0603 fuse products.

Applications

Secondary protection for space constrained applications:

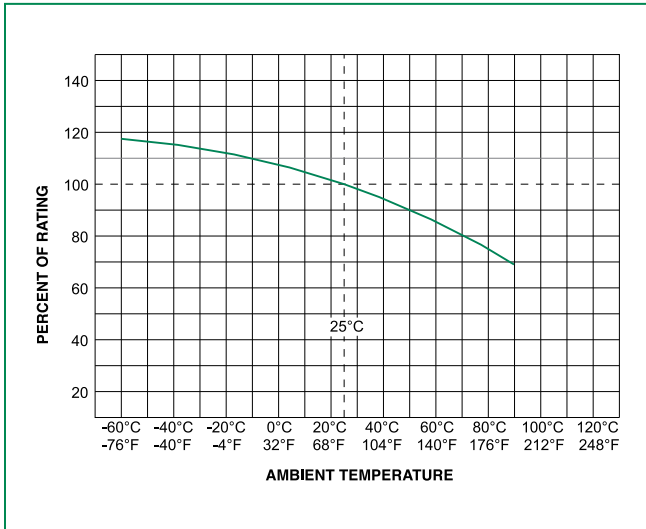
- Cell phones
- Digital cameras
- Hard disk drives.
- Battery packs
- DVD players

Electrical Specifications by Item

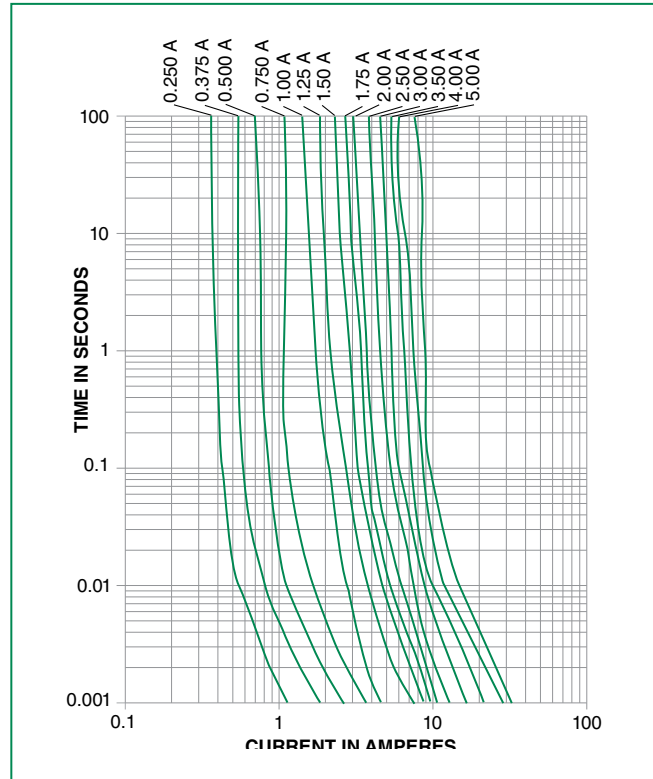
Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Nom Voltage Drop (mV)	Nom Power Dissipation (W)	Agency Approvals	
0.250	.250	32	50A @32V AC/DC	0.5450	0.0030	158.56	0.0396	x	x
0.375	.375	32		0.2900	0.0053	128.03	0.0480	x	x
0.500	.500	32		0.1870	0.0087	115.71	0.0579	x	x
0.750	.750	32		0.1170	0.0171	107.33	0.0805	x	x
1.00	001.	32		0.0710	0.0212	89.10	0.0891	x	x
1.25	1.25	32	35A @32V AC/DC	0.0530	0.0518	84.32	0.1054	x	x
1.50	01.5	32		0.0410	0.0766	81.14	0.1217	x	x
1.75	1.75	32		0.0320	0.0903	78.75	0.1378	x	x
2.00	002.	32		0.0300	0.1103	78.22	0.1564	x	x
2.50	02.5	32		0.0220	0.1440	76.10	0.1903	x	x
3.00	003.	32		0.0180	0.2403	75.04	0.2251	x	x
3.50	03.5	32		0.0150	0.4306	74.25	0.2599	x	x
4.00	004.	32		0.0130	0.5760	73.72	0.2949	x	x
5.00	005.	32		0.0090	0.9000	72.71	0.3635	x	x

1. Measured at 10% of rated current, 25°C. 2. Measured at rated voltage.

Temperature Derating Curve



Average Time Current Curves



Soldering Parameters - Wave Soldering

Reflow Condition	Pb - Free assembly	
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 - 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)	5°C/second max	
$T_{s(max)}$ to T_L - Ramp-up Rate	5°C/second max	
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 - 150 seconds
Peak Temperature (T_p)	250 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t_p)	20 - 40 seconds	
Ramp-down Rate	5°C/second max	
Time 25°C to peak Temperature (T_p)	8 minutes Max.	
Do not exceed	260°C	

